EAST Search History

EAST Search History (Prior Art)

Ref#	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
.1	1	"20040011288" pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/07 17:13
1	1	(*6648121*), PN	USPAT; USOCR	OR	OFF	2009/02/19 16:58
2	1180	"ciba specialty chemicals corporation".as.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:03
3	5	"oba specialty chemicals corporation" as, and strongly adherent coatings	US PGPUB; USPAT; FPRS, EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
4	5	"oba specialty chemicals corporation" as, and strongly adherent coating	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
,	1	10/566743 app.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:37
6	1	(7455891*), PN	USPAT; USOCR	OR	OFF	2009/02/20 11:00
7	8	((7455891") or ("6251963") or ("646228") or ("6515051") or ("6803392") or ("6733847") or ("6549121") or ("6968362")).PN	USPAT; USOCR	OR	OFF	2009/02/20 11:09
3	9	((7455991") or ("6251963") or ("6466229") or ("6515051") or ("6803392") or ("6733947") or ("6549121") or ("6368362") or ("6369362") or ("6269362"). PN.	USPAT; USOCR	OR	OFF	2009/02/20 11:14
9	108	["368981" "396305" "402679" "4199421" "4226765" "4246315" "4275064" "4275689" "4292152" "4299738" "4319688" "4324744" "4347160" "4395109" "4466989" 4533652" "4567106" "4681905" "4684679" "4684680" "47176524" "4757533" "4762625" "4691161" "4691161" "4691164" "4691064" "4691065" "4684679" "4684680" "5108835" "5116534" "5153284" "5166355" "5168087" "5196142" "5218009" "5256988" "525403" "5273314" "5280124" "6292890" "5330539" "5390500" "5399770" "5463549" "5467299" "5472992" "5504260" "561941" "5548477 "5554760" "5553426" "5574166" "5607987" "5460888" "5457299" "5472990" "5955514" "5099122" "6190423" "6329445" "6344605" "6351926" 6367065" "6399805" 6407254" "644512" "6733847" 78083985" "6808392" "5745591") URFN.	ius-Popub; iuspat; usocr	ADJ	ON	2009/02/20 11:21
10	15	["4199421" "4246315" "4466933" "4567106" "4990364" "5053246" "5252403" "6099122" "6548121" "6733847").PN. OR ("6548121" "6733847" "7455891").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/02/20 11:22
11	21169	4271533,535,536,517,407,1-412,5,532- 559,517,509,512,513,517,518,519,520,535,536,538,551,553,554,556,407.2,409,412,412.1,419.2 ods. or 430/311.ods.	US-PGPUB; USPAT; FPRS, EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27

S12	5299	427/533,509.cds. or 430/311.cds.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27
313	211	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metalized with (organic or polymer) with substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
14	139	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate and @PY<*2004*	US-PGPUB; USPAT; FPRS; EPO; JPO; DERIWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
15	13	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate and @PY<"2004" and S11	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
316	7	circuit and photoinitiator with adhesion with metal	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 16:56
317	183	jarcuit and photoinitiator with adhesion and (metal or copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
18	13	circuit and photoinitiator with adhesion with (metal or copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
319	613	circuit and photoresist with adhesion with (metal or copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
20	283	corcuit and photoresist with adhesion with (metal or copper) and plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
21	47	isrcuit and photoresist with adhesion with (metal or copper) with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:19
22	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) with adhesion with (metal or copper) with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34

\$23	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) and adhesion with (metal or copper) with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DEPWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S24	1116	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV)	US-PGPUB; USPAT; FPRS; EPO; JPO; DEPWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
25	46	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S26	10	solder mask with UV with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:40
\$27	2	"2000129322" dd	US-PGPUB; USPAT; FPRS; EPO; JPO; DEPWENT; IBM_TDB	ADJ	ON	2009/02/20 17:42
328	13	solder mask with (ovd or evaporate or pvd)	US-PGPUB; USPAT; FPRS; EPO; JPO; DEFWENT; IBM_TDB	ADJ	ON	2009/02/20 18:38
529	692	solder with (ovd or evaporate or pvd)	US-PGPUB; USPAT; FPRS; EPO; JPO; DEFWENT; IBM_TDB	ADJ	ON	2009/02/20 18:41
330	5	solder with (ovd or evaporate or pvd) with (photopolymerizble or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DEPWENT; IBM_TDB	ADJ	ON	2009/02/20 18:43
331	149	isolder with (ovd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DEFWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
332	12645	imetal with (ovd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DEPWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
\$33	45	solder with (ovd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44

S34	580	orouit board and (metal or solder or context or electrode or copper) with (ovd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist) and @PY< '2004'	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
335	25	circuit board and (metal or solder or contact or electrode or copper) with (oud or evaporate or pvd) with (photopolymerizable or UV or iphotoinitiator or photoresist) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
336	3	wiring board and (metal or solder or contact or electrode or copper) with (ovd or evaporate or pvd) with (photopolymerizible or UV or iphotoinitiator or photoresist) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:58
337	121	circuit board and (metal or solder or contact or electrode or copper) with (oud or evaporate or pvd) and (photopolymerizible or UV or iphotoinitiator or photoresist) and @PY< "2004" and cmp	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 19:05
338	1	("6524950"), PN	USPAT; USOOR	OR	OFF	2009/02/20 19:21
339	600	;photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
340	189	sphotoresist with (lift off or liftoff) and polymer\$2 with substrate and metal and @PY< "2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
341	12	shotoresist with (lift of or liftoff) and polymer\$2 with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY< "2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:25
42	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY< 2003*	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
343	0	photoresist with (lift of or liftoff) and flexible with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<*2004*	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
844	73	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34

S45	1721	(lithography or photoresist) with (lift off or liftoff) and (polymer\$2 or metal\$3 or glass or metal oxide) with substrate and @PY< 2004*	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:42
346	132	(lithography or photoresist) with (lift off or liftoff) and (polymer\$2 or metal\$3 or glass or metal oxide) with substrate and (sputter or evaporate) with (metal or half-metal) and @PY< "2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:43
347	265	427/98.5 ods	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:01
548	95	427/96.5 cds. and (resist or photoinitiator)	US-PGPUB; USPAT; FPRS; EPO; JPO; DEPWENT; IBM_TDB	ADJ	ON	2009/02/23 14:02
349	26	427/98.5 cds. and (resist or photoinitiator) and plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DEPWENT; IBM_TDB	ADJ	ON	2009/02/23 14:03
350	2	10/502208.app.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 15:36
351	1	trimethylbenzsyl allyl phenyl phosphine oxide	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/24 13:17
352	12	["20020026049" "20050147919" "6399805" "6548121" "6589550" "6733847"), FN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/25 12:09
S53	2	(09/871373 10/502208),APP.	USPAT; USOCR	ADJ	ON	2009/02/25 12:10
 354	1	wo-0024527-\$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DEPWENT; IBM_TDB	ADJ	ON	2009/02/25 14:05
955	0	EP-0475592-\$ did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 12:27

S56	0	EP-0475592.did	US-PGPUB; USPAT; FPRS; EPC; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 12:27
357	0	EP0475592 did.	US-PGPUB; USPAT; FPRS; EPC; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 12:27
558	2	"US 20060257681"	US-PGPUB; USPAT; USCOR; DERIWENT	ADJ	ON	2010/03/24 14:32
859	22	radiation with curing with dosage with crosslinking	US-PGPUB; USPAT; FPRS; EPC; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/03/24 15:58
S60	98	primer with photoinitiator with (irradiat\$3 or cur\$3 or crosslink\$3)	US-PGPUB; USPAT; FPRS; EPC; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 11:44
S61	2	jp-2001083901-\$, did.	US-POPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 12:23
S62	1	2001-338877.NFAN.	DERWENT	ADJ	ON	2010/04/01 12:24
S63	1	2001-338377.NFAN.	DERWENT	ADJ	ON	2010/04/01 12:24
S64	150	4271 492 cds.	US-PGPUB; USPAT; FPRS; EPC; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:08
S 65	655	4271487 cds.	US-PGPUB; USPAT; FPRS; EPC; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:24
S66	1148	4271508; cds.	US-PGPUB; US-PAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:27
S67	775	427/510.cds.	US-PGPUB; USPAT; PPPS; EPO; JPO; DEPWENT; IBM_TDB	ADJ	ON	2010/04/01 17:27

S68	748	427/517-519.cds.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/01 17:27
S69	115	427/517-519.cds. and primer	US-PGPUB; USPAT; FPRS, EPO; JPO; DERIWENT; IBM_TDB	ADJ	ON	2010/04/01 17:27
370	1	[74,634,602"],PN	USPAT; USOCR	OR	OFF	2010/04/02 08:51
371	31	[("3876452" "3899611" "4025407" "4128600" "4169732" "4205018" "4295947" "4342793" "4374963" "4391855" "4425207") PN OR ("4634602") UPPN	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 09:01
S77	15	["2873241" "3036830" "3892575" "4303697").PN. CR ("4778724").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 10:34
578	15	["2873241" "3088791" "3131139" "3453195"), PN. OR ("3892885"), URPN	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 11:25
379	23	["3661614" "418451" "4190631" "4197335" "4198465" "4218294" "4222335" "4264656" "4384026" "4396678").PN. CR ("4902578").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 15:51
381	0	DE-19953433-\$.did	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 16:55
82	0	[DE:1995003433-\$.did	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 16:56
383	0	DE-95003433-\$.did	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 16:56
S84	0	DE-953433-\$.did.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 16:56
385	1611	427/508-510.ods.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 17:00
386	204	427/508-510.cds. and metal\$4 and primer	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 17:01
387	148	427/508-510.cds. and metal\$4 with (coating or layer or film) and primer	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/02 17:01
388	7	427/509-510.cds. and metal\$4 with (coating or layer or film) and primer with (\$5intilator) with (cur\$3 or crosslink\$3)	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 15:48
389	8	427/509-510 cds, and metal\$4 and primer with (\$5initiator) with (cur\$3 or crosslink\$3)	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 15:51
390	185	427/508-510.cds. and metal\$4 with substrate and (\$5initiator) with (our\$3 or crosslink\$3)	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 15:51
391	0	427/508-510.cds. and metal\$4 with substrate and (multicoat\$3 or multilayer) and (\$5initiator) with cur\$3 with uncur\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 16:41
392	2	427/508-510.cds, and (multicoat\$3 or multilayer) and (\$5initiator) with cur\$3 with uncur\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 16:41
593	2	427/508-510.cds. and (multicoat\$3 or multilayer) and (\$5initiator) with cur\$3 with (stable)	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 16:42
94	57	427/508-510.cds, and (multicoat\$3 or multilayer) and photoinitiator with cur\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 16:42
395	49	427/508-510.cds. and (multiceat\$3 or multilayer) and photoinitiator with cur\$3 and metal\$4	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 16:43

396	0	427/508-510.cds. and (multicoat\$3 or multilayer) and photoinitiator with partial\$2 cur\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
97	2	427/509-510.cds. and photoinitiator with partial\$2 cur\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
98	4	427/508-510.cds. and photoinitiator with partial\$2 near5 cur\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
99	5	427/508-510.ods. and partial \$2 near5 cur\$3 with unsaturated	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:20
3100	195	427/508-510.cds. and partial\$2 near5 cur\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:23
101	109	427/508-510.cds. and partial\$2 near5 cur\$3 and photoinitiator	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:23
102	151	427/508-510.cds. and partial\$2 near5 cur\$3 and metal\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:23
3103	148	427/509-510.cds. and metal\$4 with (coating or layer or film) and primer	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
104	126	427/508-510.cds. and partial\$2 near5 cur\$3 and metal\$3 not \$103	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
105	22	427/509-510.cds. and partial\$2 near5 cur\$3 and metal\$3 not S103 and multilayer	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
106	23	427/509-510.cds. and partial\$2 near5 cur\$3 and metal\$3 not \$103 and multilayer\$3	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/05 17:24
ii 07	1]wo-0232201-\$,dd	US-PGPUB; USPAT; FPRS, EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/07 09:32
108	2	jp-2001217529-\$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/07 09:42
109	2	jp-2001046940-\$.did.	US-PGPUB; USPAT; FPRS, EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/04/07 09:46
3110	1	2001-567293.NFAN.	DERWENT	ADJ	ON	2010/04/07 09:48
3111	5	427/509-510.cds. and metal\$3 with (evaporat\$3 or sputter\$3) and multilayer\$3 and ("UV/VIS" or UV or ultraviolet) with cur\$4 and photoinitiator and acrylate	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/04/07 13:57

EAST Search History (Interference)

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4/7/2010 5:17:43 PM

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